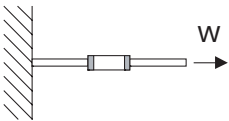
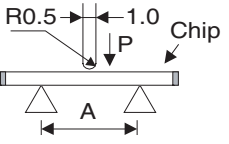


■ PERFORMANCE TESTS

TEST	SPECIFICATION	TEST CONDITION		
Solderability	* More than 90% of the terminal electrode will be covered with fresh solder.	Solder Temperature: $240 \pm 5^{\circ}\text{C}$		
Soldering Heat Resistance	* The chip will not crack. * More than 75% of the terminal electrode will be covered with solder.	Solder Temperature: $255 \pm 5^{\circ}\text{C}$ Dip Time: 3 ± 1 Seconds		
Terminal Strength	* The terminal electrode will not break and the ferrite will not be damaged. 	TYPE	KGF	Time(sec)
		GMLI-160808	0.6	30 ± 5
		GMLI-201209		
		GMLI-201212	1.0	
GMLI-321611				
Bending Strength	* There will be no mechanical damage. * The ferrite will not be damaged. 	TYPE	A(mm)	KGF
		GMLI-100505	0.4	0.2
		GMLI-160808	1.0	0.6
		GMLI-201209		
		GMLI-201212	1.4	1.0
GMLI-321611	2.0	2.0		

■ CLIMATIC TESTS

TEST	SPECIFICATION	TEST CONDITION
Thermal Shock (Temperature Cycle)	There shall be no mechanical damage. Inductance shall be within 10% of the initial value.	* Temperature: -40°C then 85°C for 30 minutes each. Total Cycles: 100
Humidity Resistance	Q-value shall be within 30% of the initial value.	* Temperature: 60°C * Humidity: 95% RH * Time: 1000 ± 12 hours
High Temperature Resistance		* Temperature: $85^{\circ}\text{C} \pm 2^{\circ}\text{C}$ * Time: 1000 ± 12 hours
Low Temperature Resistance		* Temperature: $-40^{\circ}\text{C} \pm 2^{\circ}\text{C}$ * Time: 1000 ± 12 hours

NOTE: Operating Temperature Range: -55°C TO $+125^{\circ}\text{C}$

Storage Condition: The temperature should be within -40°C TO $+85^{\circ}\text{C}$ and humidity should be less than 75%RH. The product should be used within 6 months from the time of delivery.